# Enhanced microchannel cooling for high-power semiconductor diode lasers

**SPIE LASE 6876-5** 

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 nLight Photonics

n L I G H T

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- Objective
- System Configuration & Simulation
- System Modifications
- Results & Discussion
- Conclusions & Recommendations

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# Objective

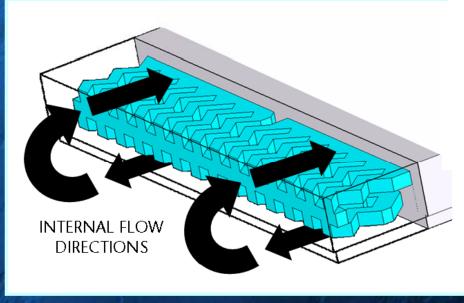
- Microchannel cooler analysis
- Using computational fluid dynamics
- Improve performance

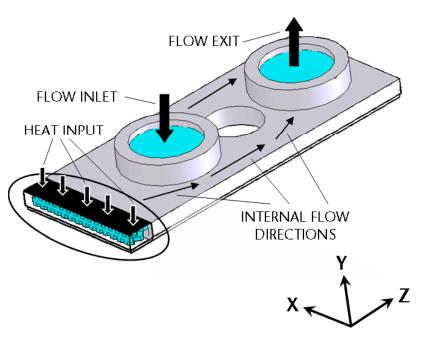
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## System Configuration

Microchannel Cooler Schematic





#### Simulations

FLUENT 6 CFD Software

• 3-D

Steady-state

#### Simulations

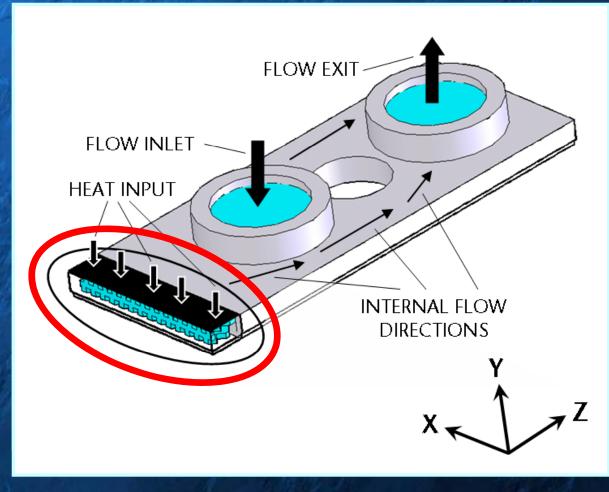
- Water flow
  - 200 ml/min
  - $-T_{IN} = 24 \, ^{\circ}\text{C} \, \text{\& P}_{IN} = 36 \, \text{PSI}$
- Heat input
  - Constant & uniform heat flux
  - 670 W/cm<sup>2</sup>
- Coupled heat transfer: fluid-solid

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## System Modifications

EXISTING SYSTEM

WIDE STRAIGHT CHANNEL

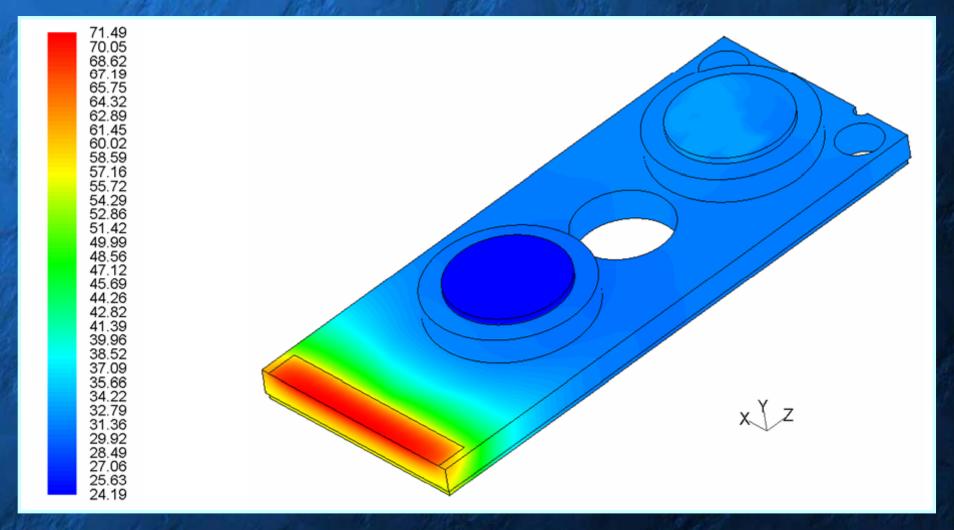


SYMMETRIC SYSTEM

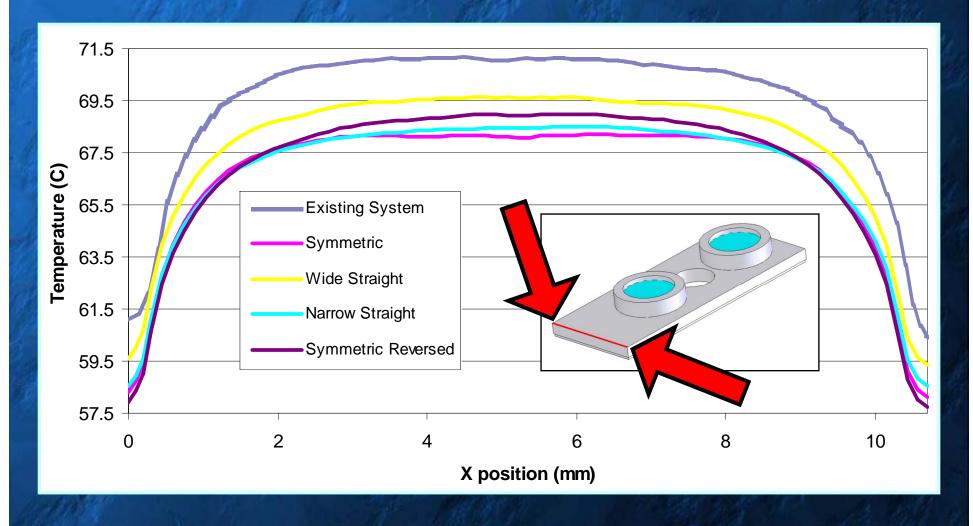
NARROW STRAIGHT CHANNELS

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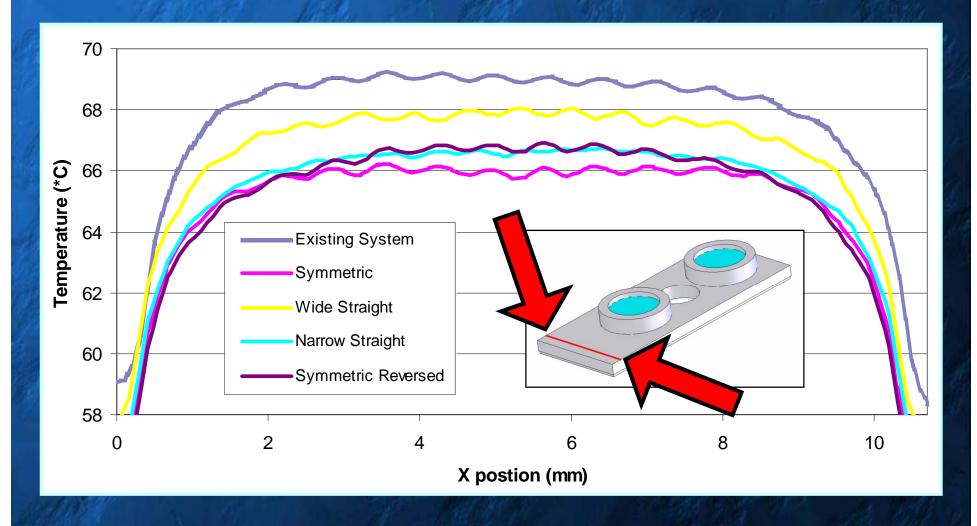
### Surface temperature profile



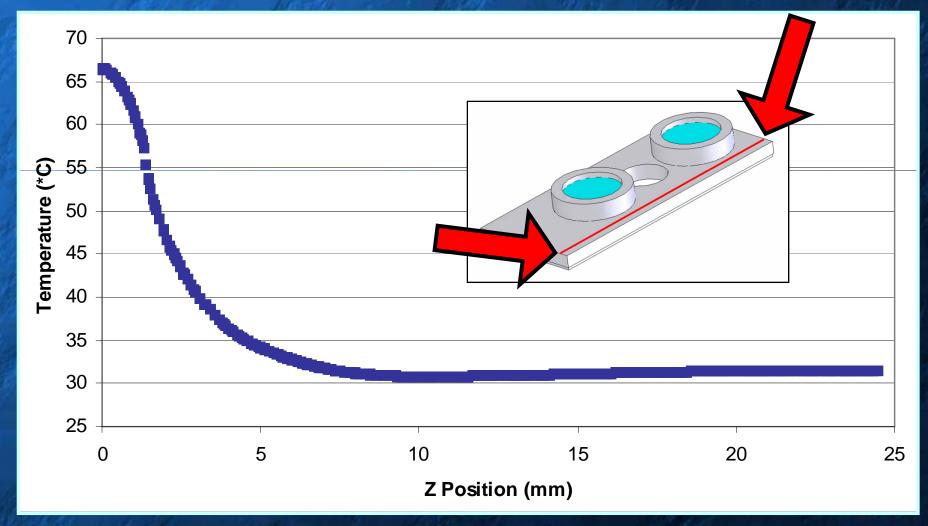
#### Surface temperature profiles



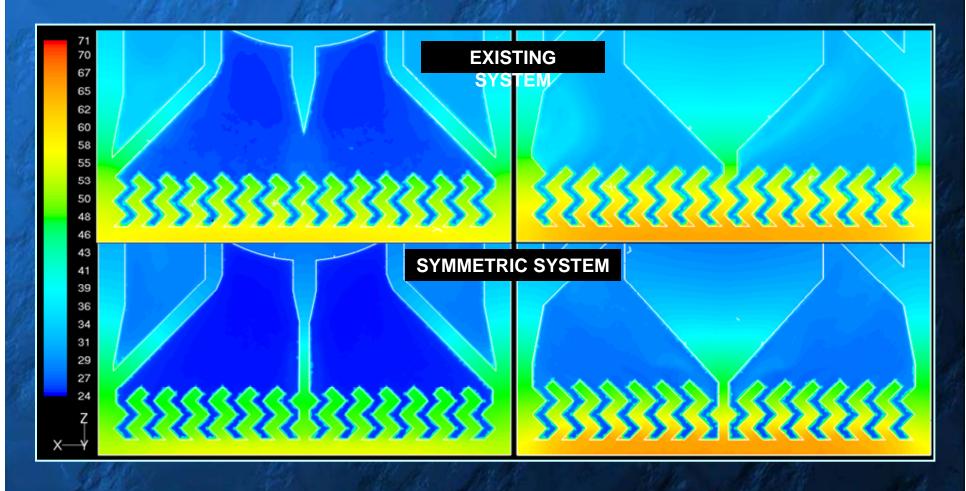
#### Surface temperature profiles



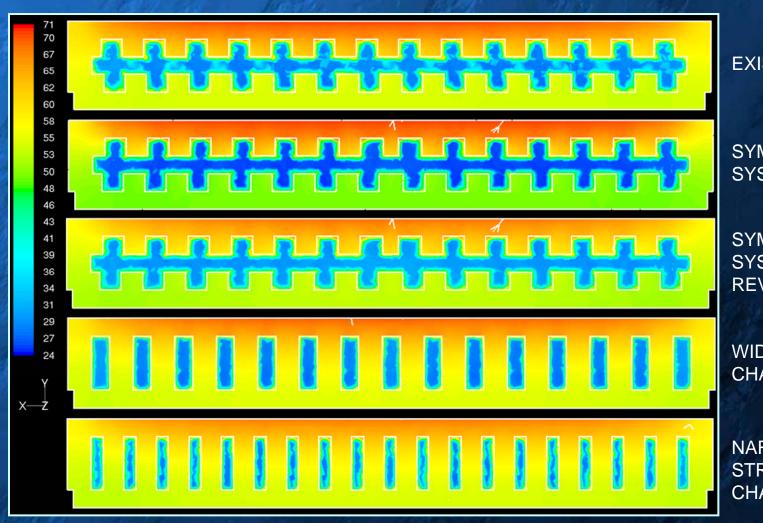
### Surface temperature profile



## Symmetry



#### Cross section temperature profiles



**EXISTING SYSTEM** 

SYMMETRIC SYSTEM

SYMMETRIC SYSTEM W/ REVERSED FLOW

WIDE STRAIGHT CHANNELS

NARROW STRAIGHT CHANNELS

# Results Summary

Channel Designs	Existing System Zig Zag	Symmetric Zig-Zag	Symmetric Zig-Zag Reversed	Wide Straight	Narrow Straight
Maximum Solid Temperature	71.2	68.2	69.0	69.6	68.5
at Heat Input (*C)					
Average Temperature at Heat Input (*C)	66.9	64.2	64.4	65.8	64.6
Thermal Resistance (*C-m2/W)	0.070	0.066	0.067	0.068	0.066
System Pressure Drop (psi)	14.6	14.3	14.6	4.5	5.5

# Results Summary

Channel Designs	Existing System Zig-Zag	Symmetric Zig-Zag	Symmetric Zig-Zag Reversed	Wide Straight	Narrow Straight
Maximum Solid Temperature at Heat Input (*C)	<del>71.2</del>	-4.21%	-3.0 <del>9</del> %	-2.25%	-3.7 <del>9</del> %
Average Temperature at Heat Input (*C)	66.9	-4.04%	-3.74%	-1.64%	-3.44%
Thermal Resistance (*C-m2/W)	0.070	-5.71%	-4.29%	-2.86%	-5.71%
System Pressure Drop (psi)	14.6	-2.05%	0.00%	-69.18%	-62.33%

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#### Conclusion & Recommendations

 Focus on channel designs for improvement

Designs should be symmetrical

Performance improvements/balancing